MOSFET Module

# **STARPOWER**

SEMICONDUCTOR

# MOSFET

# MD300HFC170C2S

1700V/300A 2 in one-package

## **General Description**

STARPOWER MOSFET Power Module provides very low  $R_{DS(on)}$  as well as optimized intrinsic diode. It's designed for the applications such SMPS and DC drives.

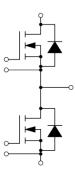
#### Features

- SiC power MOSFET
- Low R<sub>DS(on)</sub>
- Optimized intrinsic reverse diode
- Chip sintering technology
- Low inductance case avoid oscillations
- Isolated copper baseplate using AlN DBC technology

## **Typical Applications**

- Main and auxiliary AC drives of electric vehicles
- DC servo and robot drives
- Battery vehicles
- UPS equipment
- Plasma cutting

## **Equivalent Circuit Schematic**



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### **Absolute Maximum Ratings**

#### MOSFET

Symbol	Description	Value	Unit	
V <sub>DSS</sub>	Drain-Source Voltage	1700	V	
V <sub>GSSmax</sub>	Gate-Source Voltage	-8/+19	V	
V <sub>GSSop</sub>	Gate-Source Voltage	-4/+15	V	
I <sub>D</sub>	Drain Current @ $T_C=25^{\circ}C$	484	A	
	@ $T_{\rm C} = 100^{\circ} {\rm C}$	300		
I <sub>DM</sub>	Pulsed Drain Current	TBD	A	

#### **Body Diode**

Symbol	Description	Value	Unit
Is	Source Current @ T <sub>C</sub> =100°C	TBD	Α
I <sub>SM</sub>	Pulsed Source Current	TBD	Α

#### Module

Symbol	Description	Value	Unit
T <sub>jmax</sub>	Maximum Junction Temperature	175	°C
T <sub>jop</sub>	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature Range	-40 to +125	°C
V <sub>ISO</sub>	Isolation Voltage RMS,f=50Hz,t=1min	4000	V

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
D	Static Drain-Source	$I_D = 600A, V_{GS} = 15V, T_j = 25^{\circ}C$		3.33	4.33	
R <sub>DS(on)</sub>	On-Resistance	$I_D=600A, V_{GS}=15V, T_i=175^{\circ}C$		6.83		mΩ
V <sub>GS(th)</sub>	Gate-Source Threshold Voltage	$I_{D}=159mA, V_{DS}=V_{GS}, T_{j}=25^{\circ}C$	1.8	2.5	3.6	V
g <sub>fs</sub>	Forward Transconductance	$V_{DS}$ =20V, $I_{D}$ =600A		288		S
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}=V_{DSS}, V_{GS}=0V,$ $T_j=25^{\circ}C$			240	μΑ
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=V_{GSS}, V_{DS}=0V,$ $T_i=25^{\circ}C$			600	nA
R <sub>Gint</sub>	Internal Gate Resistance			0.4		Ω
C <sub>iss</sub>	Input Capacitance			42.4		nF
C <sub>oss</sub>	Output Capacitance	$V_{GS} = 0V, V_{DS} = 1000V,$		1.11		nF
C <sub>rss</sub>	Reverse Transfer Capacitance	f=100kHz		0.04		nF
Qg	Total Gate Charge			1170		nC
$Q_{gs}$	Gate-Source Charge	$I_{D}$ =600A, $V_{DS}$ =1200V,		354		nC
$Q_{gd}$	Gate-Drain ("Miller") Charge	V <sub>GS</sub> =-4/+15V		324		nC

#### **MOSFET Characteristics**

### Body Diode Characteristics $T_F=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
$V_{SD}$	Diode Forward Voltage	$I_{s}=300A, V_{GS}=-4V, T_{j}=25^{\circ}C$		4.60		- V
		$I_s=300A, V_{GS}=-4V, T_i=175^{\circ}C$		4.10		
t <sub>rr</sub>	Diode Reverse Recovery Time	V <sub>R</sub> =800V,I <sub>S</sub> =600A,		43		ns
Qr	Diode Reverse Recovery Charge	-di/dt=18000A/μs, V <sub>GS</sub> =-4V,		10.8		μC
I <sub>RM</sub>	Peak Reverse Recovery Current	T <sub>j</sub> =175°C		390		А

#### Module Characteristics T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter		Тур.	Max.	Unit
<b>R</b> <sub>thJC</sub>	Junction-to-Case(Mosfet) 0.072		K/W		
R <sub>thCH</sub>	Case-to-Heatsink (Mosfet)		0.020		V/W
	Case-to-Heatsink (per Module)		0.010	K/W	
М	Terminal Connection Torque, Screw M6	2.5		5.0 N.m	
	Mounting Torque, Screw M6	3.0		5.0	IN.III
G	Weight of Module		300		g

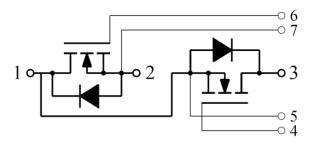
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3/5

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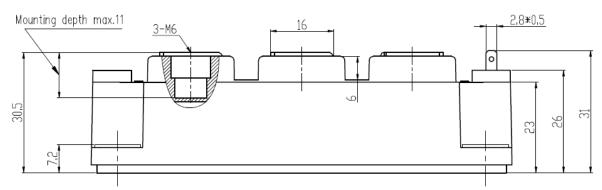
MOSFET Module

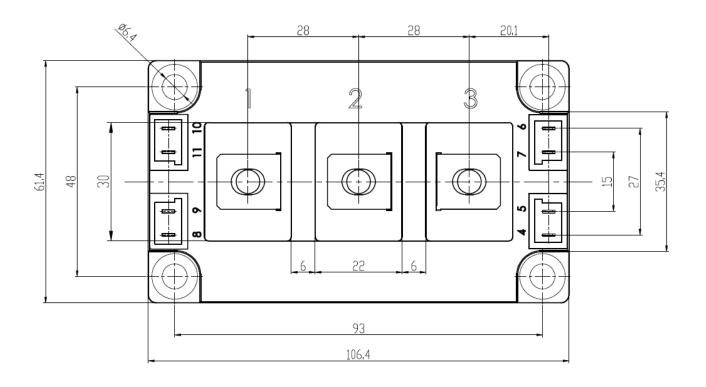
#### **Circuit Schematic**



### **Package Dimensions**

Dimensions in Millimeters





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Preliminary

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